SYSTEM RUGGED COMPUTERS

Kite-Strike



Fully Rugged Embedded Edge Supercomputer *Mini. Mighty. Modular.*

Key Product Features

- NVIDIA® Jetson AGX Xavier™ SOM
- GPU: NVIDIA® Volta Architecture, 512 CUDA Cores and 64 Tensor Cores
- CPU: 8-Core Carmel ARM v8
- Memory: 32GB
- Storage: Onboard 32GB eMMC; Internal m.2 NVME up to 1TB
- Dense I/O Including Multiple GbE, USB, CAN
- DC/DC Power Supply 28VDC Nominal
- MIL-STD-810H Shock and Vibration
- MIL-STD-461G EMI/EMC
- MIL-STD-1275E and MIL-STD-704F Power
- IP66 Sealed Dust/Water Ingress
- -40°C to +71°C Operating Temperature
- Linux Ubuntu 18.04 OS
- Foldable Handle for Easy Carry and Handling
- Expansion Slice Design for Modular System Expansion

Product Highlights

Kite-Strike™ is a next-generation embedded edge supercomputer. Integrating the NVIDIA® Jetson AGX Xavier™ system-on-module, Kite-Strike™ is purpose-built for deployment in harsh environments, offering maximum capability and reliability in a compact form factor.

Kite-Strike™ enables real-time Al inferencing and Deep Learning (DL)/ Machine Learning (ML) capabilities and provides centralized sensor ingest and data fusion support.

Kite-Strike™ provides the advanced computing capability and ruggedization demanded for mission-critical applications, and is fully configurable and modular to meet exacting customer specifications.

Kite-Strike™ is engineered and manufactured for extreme SWaP optimization and incredible compute capability, offering data center performance in a compact, fully rugged embedded edge computer.

Systel, Inc.

Phone: 877-979-7835 Email: sales@systelusa.com

www.systelusa.com

Black Anodized Machined Aluminum Exterior, Clear Alodine Interior; CARC/RAL

Finish Options Available

Ctrl/Indicator Power with Green LED

Dimensions (WxDxH) 6.75" x 6.75" x 4.00"

O-ring Sealed for IP66 Dust/ Sealing

Water Ingress Protection

Conduction/Convection with Cooling

Integrated External Rugged

Forced Air Cooling Solution

NVIDIA® Jetson AGX Xavier™

8-Core Carmel ARM v8, 64-Bit

Volta Architecture, 512 CUDA

7-Way VLIW Vision Processor

Cores, 64 Tensor Cores

Up to 4 x 4K @60 HEVC

Up to 2 x 8K @ 30 HEVC

(4) RS-232/422/485

(1) USB 3.0, (2) USB 2.0

(1) Stereo Line Out and

MIL-DTL-38999; High-

Field or Coax/DIN/BNC

Video Capture/Encode, ARINC 429, 1553, LTE, GPS,

Speed I/O May Use Circular

Numerous Options Including

Additional GbE/USB/Serial/

(2) GbE

(2) CAN 2.0

(1) HDMI/DVI

Mono Mic In

32GB I PDDR4x 2133

32GB eMMC 5.1

Environment

-40°C to +71°C, Operating

-40°C to +85°C, Storage

MIL-STD-810H Method 500.6

Humidity MIL-STD-810G Method 510.6,

Proc. I; MIL-STD-810H Method

20g @11ms; MIL-STD-810H Method 516.8, Proc. 1, 40g @ 11ms; MIL-STD-810H Method

516.8, Proc. V, 75g @ 6ms

Proc. I, Category 20 Ground

MIL-STD-1275E; MIL-STD-704F **Power**

(No Power Holdup)

EMI/EMC MIL-STD-461G RE102, RS103,

CS101, CS114, CS115, CS116,

Section 5.11

Sand and Dust MIL-STD-810G Method 510.6.

Proc. I; MIL-STD-810H Method







System-On-Module

SOM

CPU

GPU

Memory

Storage

Accelerator

Video Encode

Video Decode

System I/O

Video Output

Connectors

Expansion

Vision

Serial

USB

CAN

Audio

Ethernet





SOM; m.2 NVME up to 1TB; Removable Options

Available

Power

Power

Galvinically Isolated DC/ DC Power Supply; Wide

Range Voltage with 28VDC Nominal Conforming to MIL-

STD-1275E

Fluids/Rain

Temperature

Altitude

Procedure I and II, 30,000 Ft...

507.6, Proc. I Up to 95% RH

Non-Condensing

MIL-STD-810G Method 516.7, Shock

Vibration MIL-STD-810G Method 514.7,

> Vehicles-Ground Mobile; MIL-STD-810H Method 514.8, Proc. I,

Category 4, C-IV

CE101, CE102; MIL-STD-464C

510.7, Proc. II; IP66 Sealed

MIL-STD-810G Method 504.2,

Proc. II; MIL-STD-810H Method

506.6., Proc. I



CAN